

Amphenol

Amphenol Booth #4015



- **Supporting Next Generation 800G Applications**
 - OSFP (Octal Small Form Factor Pluggable) and QSDP-DD (Quad Small Form Factor Double Density) with eight high speed electrical lanes currently supporting 800 Gbps (8x112G).
 - Passive copper cable solutions up to 2.0 meters
- **Superior Thermal and Electrical Connector Performance**
 - Available in both SMT ganged and stacked pressfit configurations – supporting 36 ports per 1U front panel.
 - Supports cooling of 16W+ of power per port.



- **Amphenol is participating in the following Demo's with OIF –**
 - CEI-112G Demo featuring Amphenol 112G DACs, 112G OSFP HCB, 112G OSFP MCB
 - Common Management Interface Specification (CMIS) implementations featuring an Amphenol sample 400G QSFP-DD AOC compliant to CMIS 5.0
 - Co-Packaging Architectures Demo (featuring a sample Amphenol Board showing potential solutions with our CCS socket and Densilink® to OSFP copper cable)



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- **Characterization/validation of QSFP-DD and OSFP systems**

- Utilizing Amphenol Ardent's patented TR Multicoax proven interface technology
- Allows engineers to develop and characterize systems and devices utilizing high speed ports and connectors
- Access to all 16 differential pairs (32 coax connectors)
- Ideal for 400G (8x56G) and 800G (8x112G) systems, users can easily characterize all high speed lines in a simple to use form factor

- **Designed to be compliant to IEEE 802.3ck and OIF CEI-112G-VSR performance requirements**

- Maximum IL at 26.56 GHz from paddle card mating interface to coax connector: 2.5dB
- Maximum Differential Impedance Variation for all transitions: $\pm 10 \Omega$
- Maximum Phase Length Variation within a differential pair: ± 1 ps
- Supports QSFP-DD and OSFP MSA mechanical module requirements

